

SOT1369-5

HVQFN40, plastic, thermally enhanced very thin quad flat, non-leaded package; 40 terminals; 0.4 mm pitch; 5 mm x 5 mm x 0.85 mm body

8 October 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN40
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	20-09-2019
Manufacturer package code	98ASA01371D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.9	5	5.1	mm
package width	4.9	5	5.1	mm
seated height	0.8	0.85	1	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	40	-	



HVQFN40, plastic, thermally enhanced very thin quad flat, non-ledged package; 40 terminals; 0.4 mm pitch; 5 mm x 5 mm x 0.85 mm body

2 Package outline

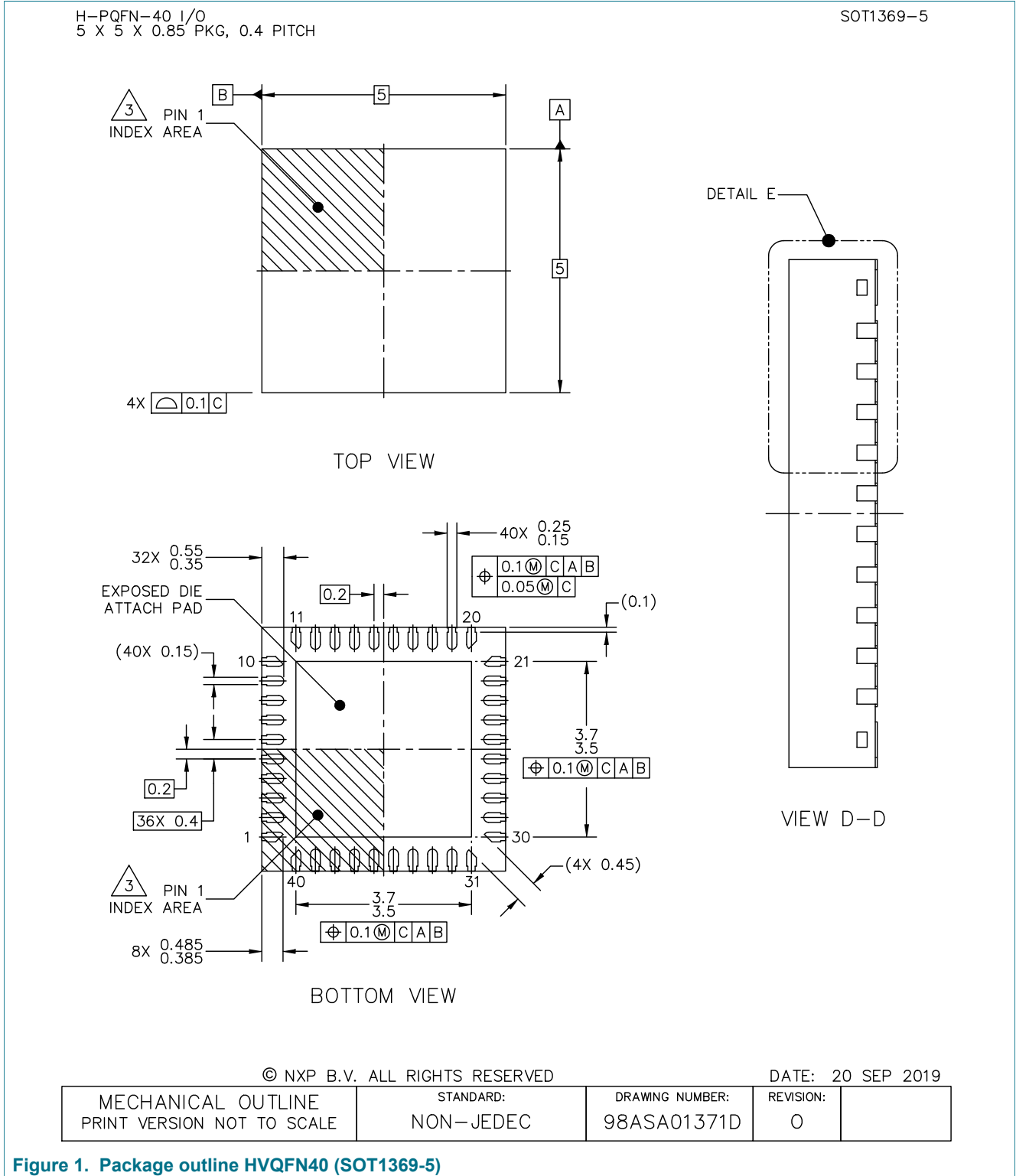
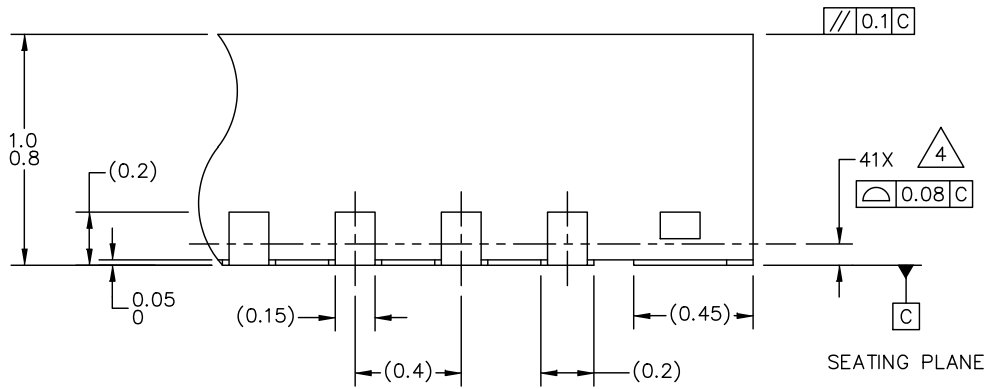


Figure 1. Package outline HVQFN40 (SOT1369-5)

HVQFN40, plastic, thermally enhanced very thin quad flat, non-leaded package; 40 terminals; 0.4 mm pitch; 5 mm x 5 mm x 0.85 mm body

H-PQFN-40 I/O
5 X 5 X 0.85 PKG, 0.4 PITCH

SOT1369-5



DETAIL E
VIEW ROTATED 90° CW

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DATE: 20 SEP 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01371D	REVISION: 0	
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Figure 2. Package outline detail of HVQFN40 (SOT1369-5)

HVQFN40, plastic, thermally enhanced very thin quad flat, non-leaded package; 40 terminals; 0.4 mm pitch; 5 mm x 5 mm x 0.85 mm body

3 Soldering

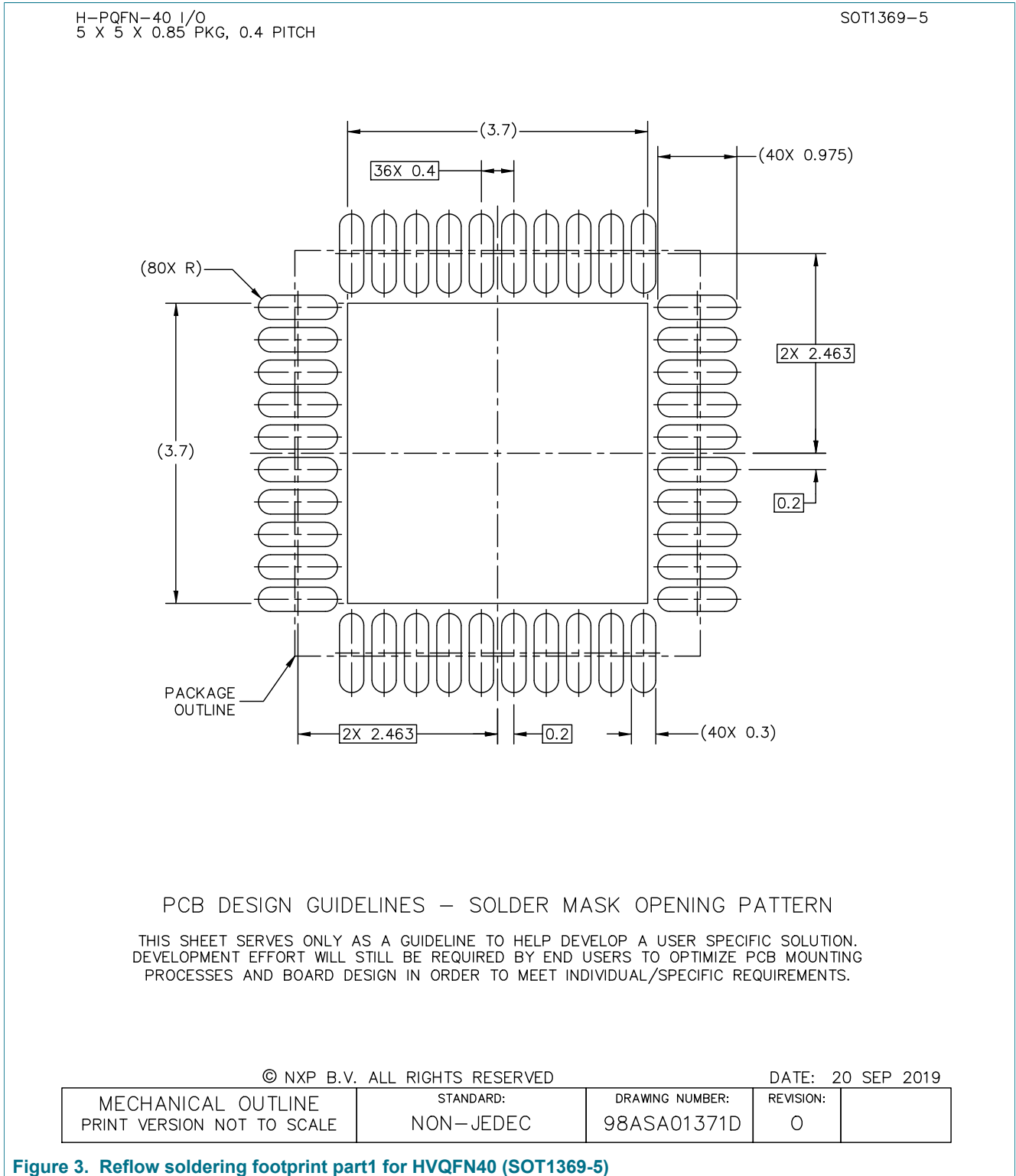


Figure 3. Reflow soldering footprint part1 for HVQFN40 (SOT1369-5)

HVQFN40, plastic, thermally enhanced very thin quad flat, non-leaded package; 40 terminals; 0.4 mm pitch; 5 mm x 5 mm x 0.85 mm body

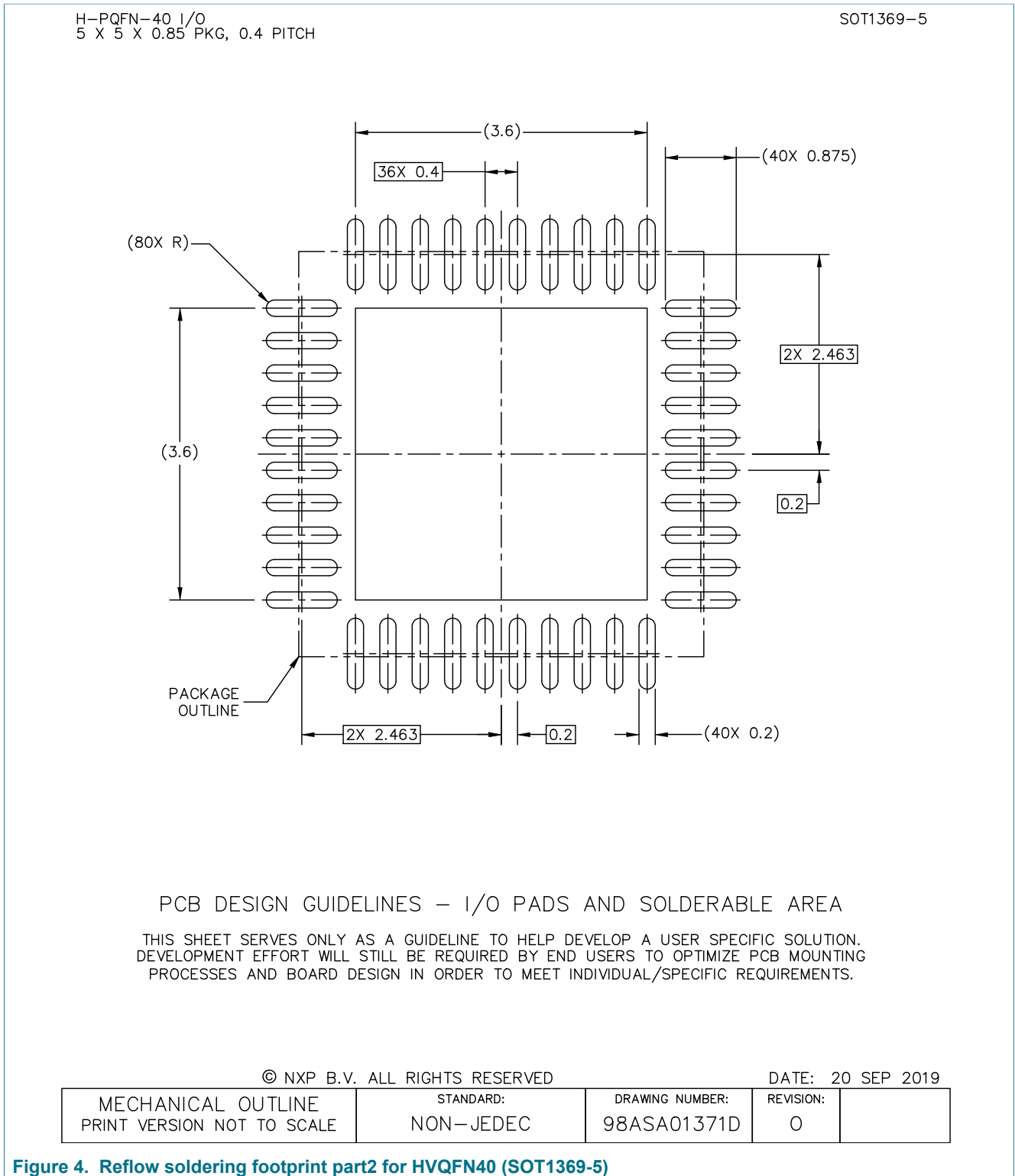


Figure 4. Reflow soldering footprint part2 for HVQFN40 (SOT1369-5)

HVQFN40, plastic, thermally enhanced very thin quad flat, non-leaded package; 40 terminals; 0.4 mm pitch; 5 mm x 5 mm x 0.85 mm body

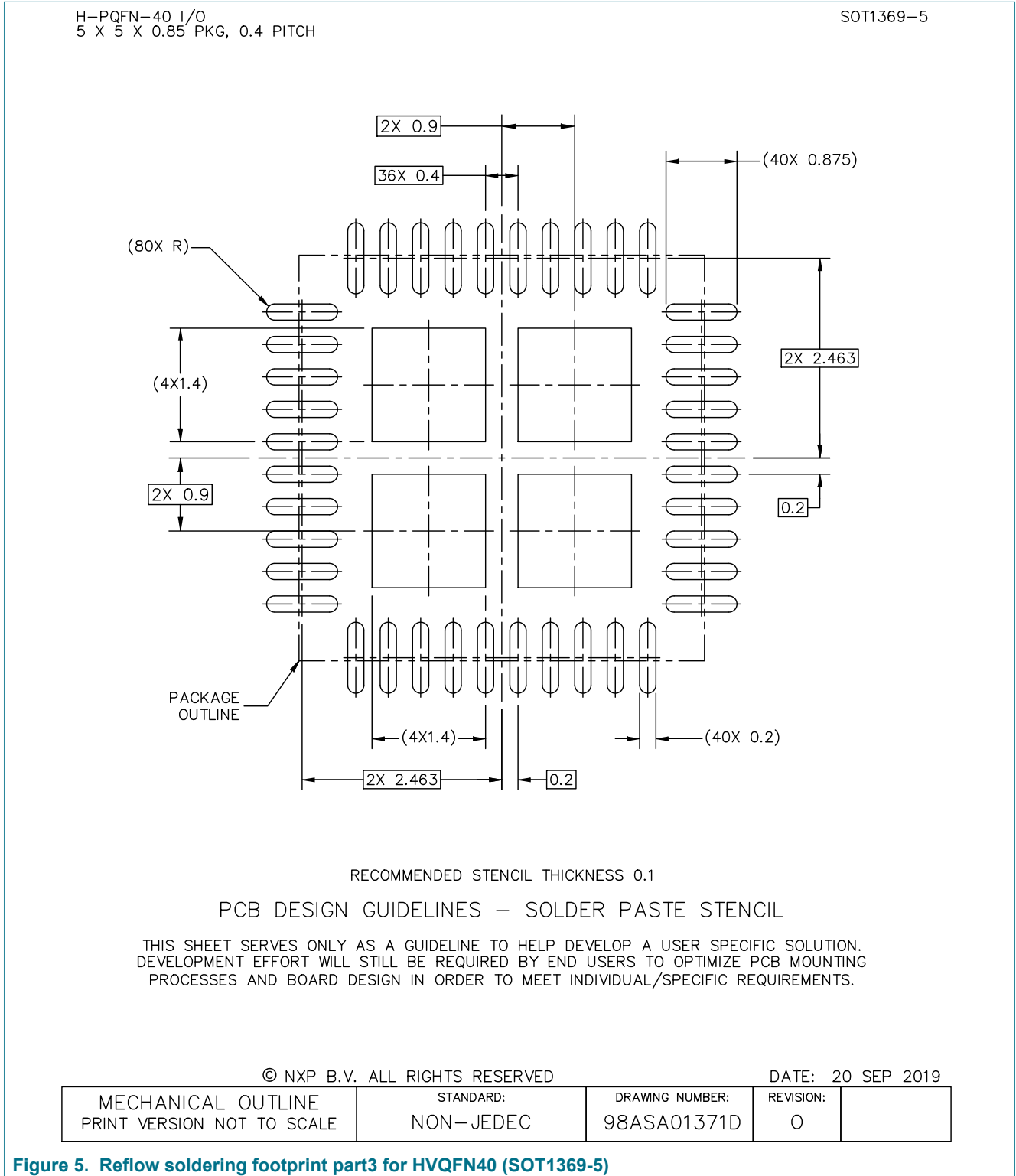


Figure 5. Reflow soldering footprint part3 for HVQFN40 (SOT1369-5)

HVQFN40, plastic, thermally enhanced very thin quad flat, non-leaded package; 40 terminals; 0.4 mm pitch; 5 mm x 5 mm x 0.85 mm body

H-PQFN-40 I/O
5 X 5 X 0.85 PKG, 0.4 PITCH

SOT1369-5

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.15 MM.

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Figure 6. Package outline note HVQFN40 (SOT1369-5)

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4 Legal information

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